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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Charles W.C. Lin
Title: BUMPLESS FLIP CHIP ASSEMBLY WITH SOLDER VIA
Serial No.: 09/852,824 Filed: May 10, 2001
Examiner: Unknown Group Art Unit: 2812
Atty. Docket No.: P002-2

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ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

Pursuant to Applicant's duty of disclosure under 37 C.F.R. § 1.56 and §§ 1.97-1.98,
Applicant hereby provides a copy of the documents identified on the enclosed Form PTO-1449.

The filing of this Information Disclosure Statement shall not be construed as a representation that a search has been made, an admission that any of these documents, alone or in any combination, is considered to be material to patentability, an admission that any of these documents is prior art as to the above-identified application, or an admission against interest in any manner.

This Information Disclosure Statement is filed before the mailing date of a first Office Action on the merits. Accordingly, no fee is due. 37 C.F.R. § 1.97(b)(3).



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I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on January 28, 2002.

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1/28/02
Date of Signature

Respectfully submitted,

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